

## **Abstract**

The present invention relates to a multilayer ceramic package providing an improved connection pattern structure between inside and outside terminals and a fabrication method thereof. The ceramic package internally mounts at least one component and is formed by stacking a plurality of ceramic sheets one atop another. Internal patterns are formed in at least a portion of the ceramic sheets. A lid is mounted on the layered structure above the cavity to maintain the cavity airtight. Outside connection terminals are formed in outer portions of the layered structure. Internal connection patterns are separately formed horizontally in at least two of the ceramic sheets to be electrically connected with the outside connection terminals. Inside connection terminals formed within the cavity to be electrically connected with the component and at least a portion of the internal connection pattern.